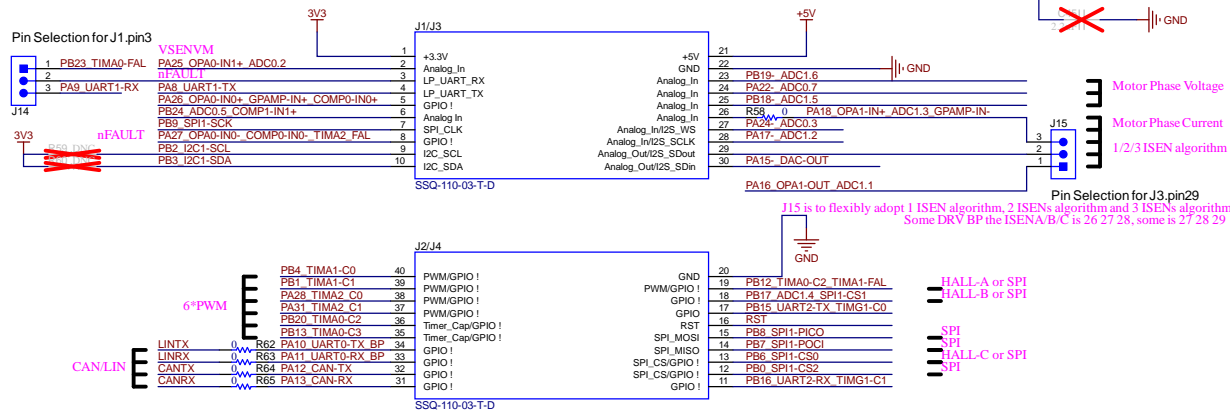


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Orderable: LP-MSPM0G3507	Designed for: Public Release	Mod. Date: 2/15/2023
TID #: N/A	Project Title: LP-MSPM0G3507	
Number: MCU098	Rev: A	Sheet Title: MSPM0G3507
SVN Rev: Not in version control	Assembly Variant: Variant 1	Sheet: 1 of 7
Drawn By: Johnson He	File: MCU098_01_MSPM0G3507_Target_Device_Sch Size: B	http://www.ti.com
Engineer: Johnson He	Contact: http://www.ti.com/support	© Texas Instruments 2022

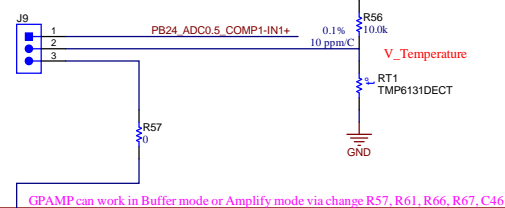
BoosterPack Connectors



Thermistor Circuit

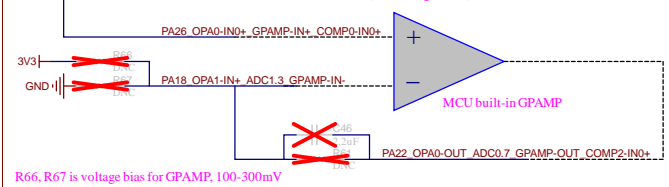
Connect J27.1 & J27.2 to enable Thermistor to ADC

Connect J27.2 & J27.3 to enable Thermistor to GMAMP



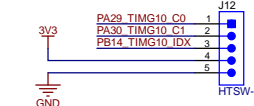
GPAMP Test Circuit

This GPAMP can be used in Thermistor or Motor Control (3 ISEN algorithm)

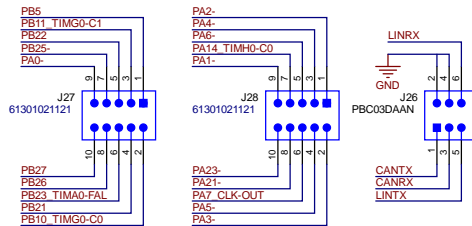


Pin headers at the Low Side of the Board

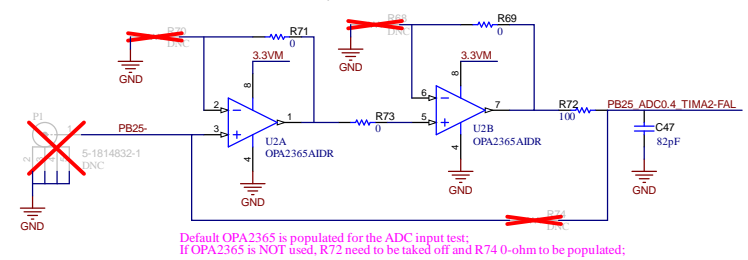
QE1 Interface



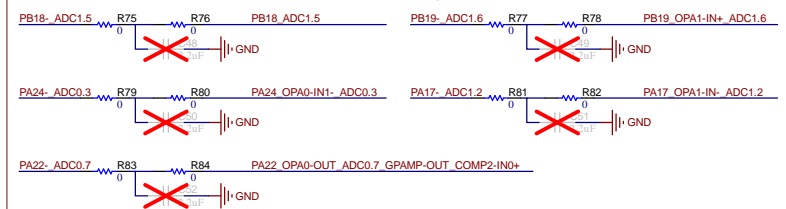
PA19, PA20 are SWDIO, SWCLK for debug/programming interface. They are on J101, pin14, pin16



ADC Input with Active Buffer

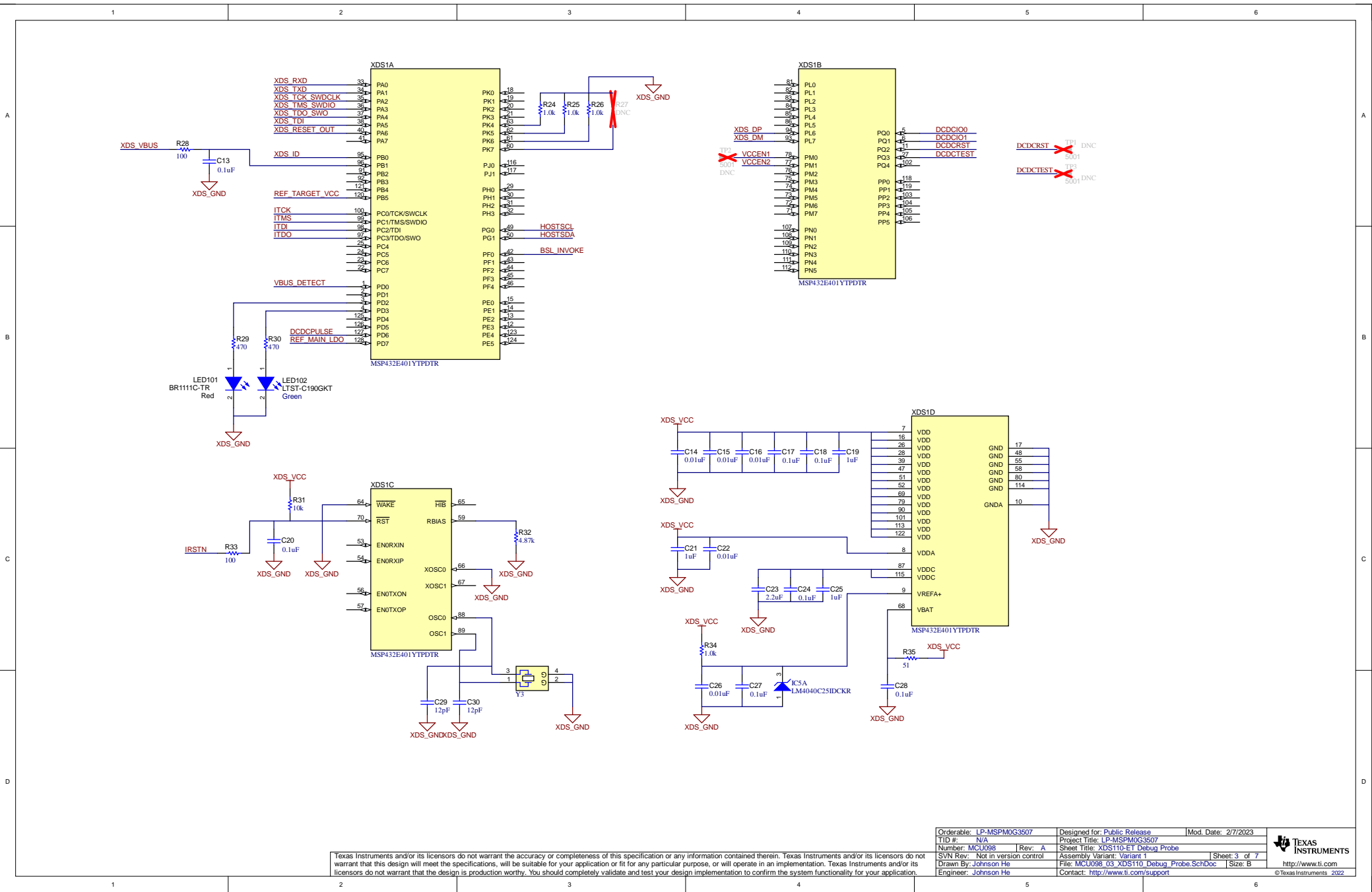


RC Filter for ADC Input

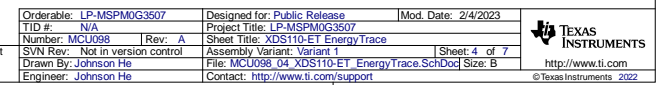


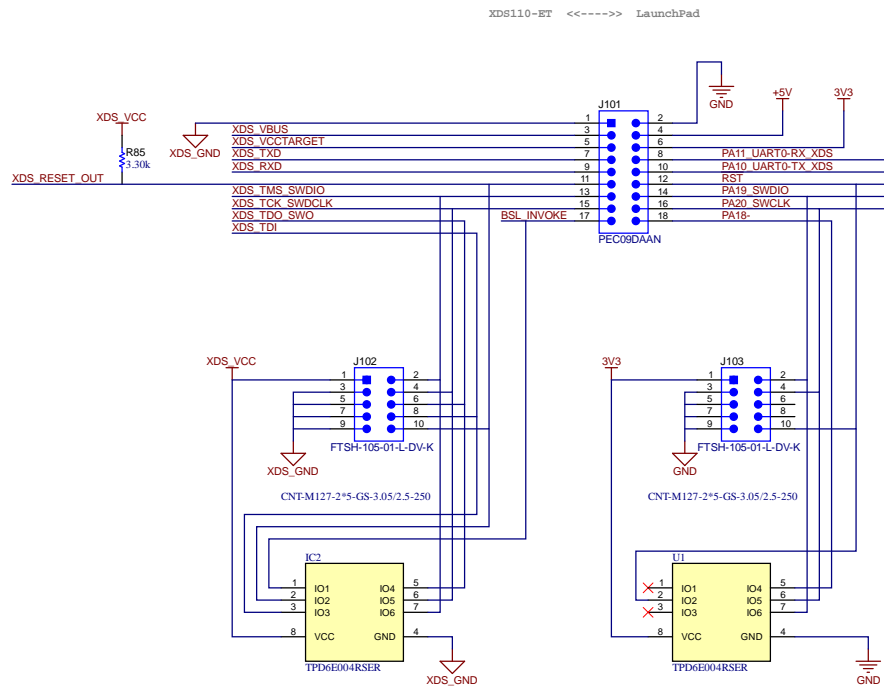
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TID #: N/A	Project Title: LP-MSPM0G3507	
Number: MCU098	Rev: A	Sheet Title: BoosterPack Connectors
SVN Rev: Not in version control	Assembly Variant: Variant 1	Sheet: 2 of 7
Drawn By: Johnson He	File: MCU098_02 BoosterPack Connectors.SchDoc	Size: B
Engineer: Johnson He	Contact: http://www.ti.com/support	



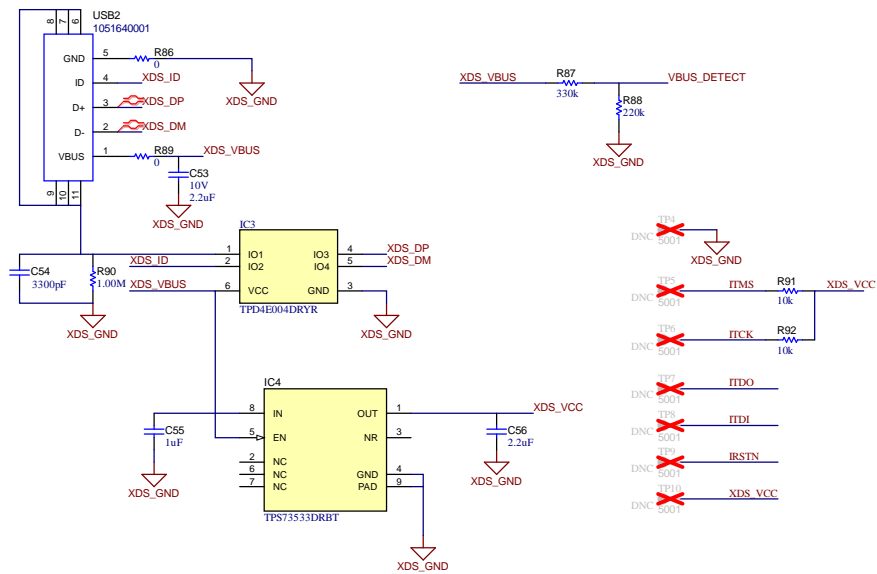
Energy measurement method protected under U.S. Patent Application 13/329,073 and subsequent patent applications





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TID #: N/A	Project Title: LP-MSPM0G3507	
Number: MCU098	Rev: A	Sheet Title: XDS110-ET Interface
SVN Rev: Not in version control	Assembly Variant: Variant 1	Sheet: 5 of 7
Drawn By: Johnson He	File: MCU098_05_XDS110_Target_Interface.SchDoc	Size: B
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TID #: N/A	Project Title: LP-MSPM0G3507	
Number: MCU098	Rev: A	Sheet Title: XDS110-ET USB Power
SVN Rev: Not in version control	Assembly Variant: Variant 1	Sheet: 6 of 7
Drawn By: Johnson He	File: MCU098_06_XDS110-ET_USB_Power.SchDoc	Size: B
Engineer: Johnson He	Contact: http://www.ti.com/support	http://www.ti.com



